

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	2	("6643099").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 10:15
L4	2	("6768628").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 10:28
L5	2	("6875475").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 10:36
L6	1	@ad<="20030416" and 'titanium carbide substrate' same 'silicon substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 10:40
L7	1	@ad<="20030416" and 'titanium carbide wafer' same 'silicon wafer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 10:40
L8	440	@ad<="20030416" and (438/52). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:31
L9	1	@ad<="20030416" and (438/52). ccls. and 'TiC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 10:55
L10	4	@ad<="20030416" and (438/52). ccls. and 'Titanium carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:05
L11	380	@ad<="20030416" and (438/50). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:05
L12	28	@ad<="20030416" and (438/52). ccls. and 'TiN'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:07

L13	580	@ad<="20030416" and (438/53). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:31
L17	47	@ad<="20030416" and 'MEMS' same 'TiN' same 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:35
L18	11	@ad<="20030416" and 'MEMS' same 'TiN' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:35
L19	0	@ad<="20030416" and 'MEMS' same 'Titanium carbide' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:35
L20	10	@ad<="20030416" and 'MEMS' same 'Titanium nitride' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:35
L21	0	@ad<="20030416" and 'MEMS' same 'Titanium boride' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:35
S1	14	((("5198390") or ("5316979") or ("5399415") or ("5426070") or ("5628917") or ("5846849") or ("6180536"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/18 13:58
S2	2	"20040207074"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/18 13:42
S3	1	"5876675".PN.	USPAT; USOCR	OR	ON	2005/11/18 13:50
S4	1	"5847454".PN.	USPAT; USOCR	OR	ON	2005/11/18 13:50
S5	1	"5690841".PN.	USPAT; USOCR	OR	ON	2005/11/18 13:51
S6	1	"5681484".PN.	USPAT; USOCR	OR	ON	2005/11/18 13:51
S7	1	"5426070".PN.	USPAT; USOCR	OR	ON	2005/11/18 13:55
S8	1	"5393375".PN.	USPAT; USOCR	OR	ON	2005/11/18 13:55
S9	1	"5198390".PN.	USPAT; USOCR	OR	ON	2005/11/18 13:56

S10	1	"5072288".PN.	USPAT; USOCR	OR	ON	2005/11/18 13:56
S11	1	"4980317".PN.	USPAT; USOCR	OR	ON	2005/11/18 13:57
S12	4246	@ad<="20030416" and (438/52). ccls. or (257/E21.218).ccls. or (438/666).ccls. or (438/702).ccls. or (438/749-750).ccls. or (438/745). ccls. or (438/739).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:05
S13	0	@ad<="20030416" and 'MEMS' same 'sustrate' with 'silicon' with 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 11:34
S14	169	@ad<="20030416" and 'MEMS' same 'substrate' with 'silicon' with 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/18 14:06
S15	58	@ad<="20030416" and 'MEMS' with 'substrate' with 'silicon' with 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/18 14:16
S16	27	@ad<="20030416" and 'actuator' with 'substrate' with 'silicon' with 'metal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/18 14:06
S18	25	@ad<="20030416" and 'MEMS' and 'metal wafer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/18 14:17
S19	941	@ad<="20030416" and 'metal wafer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 04:43
S20	471	@ad<="20030416" and 'metal' with 'wafer' and 'etch' same ('trench' or 'via') same 'anisotropic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 08:02
S21	17	@ad<="20030416" and 'metal wafer' and 'etch' same ('trench' or 'via') same 'anisotropic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:16
S22	70	@ad<="20030416" and 'etch' same 'metal wafer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 04:37

S23	574	@ad<="20030416" and 'etch' same 'metal substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 06:30
S24	106	@ad<="20030416" and 'metal substrate' and 'etch' same ('trench' or 'via') same 'anisotropic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 04:38
S25	3	@ad<="20030416" and 'metal substrate' same 'etch' same ('trench' or 'via') same 'anisotropic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 04:38
S26	435	@ad<="20030416" and 'metal substrate' with 'silicon substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 04:45
S27	13	@ad<="20030416" and 'metal substrate' with 'silicon substrate' same 'etching'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 04:45
S28	10	@ad<="20030416" and 'metal substrate' with 'silicon substrate' same 'via'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 04:45
S29	0	@ad<="20030416" and 'metal substrate' with 'silicon substrate' same 'trench'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 04:45
S30	1	"6535474".PN.	USPAT; USOCR	OR	ON	2005/11/19 04:46
S31	1	"5422505".PN.	USPAT; USOCR	OR	ON	2005/11/19 05:24
S32	1	"5289027".PN.	USPAT; USOCR	OR	ON	2005/11/19 05:24
S33	1	"5198390".PN.	USPAT; USOCR	OR	ON	2005/11/19 05:25
S34	1	"5156988".PN.	USPAT; USOCR	OR	ON	2005/11/19 05:25
S35	1	"5072288".PN.	USPAT; USOCR	OR	ON	2005/11/19 05:27
S36	1	"4845048".PN.	USPAT; USOCR	OR	ON	2005/11/19 05:43
S37	1	"4814287".PN.	USPAT; USOCR	OR	ON	2005/11/19 05:45
S38	1	"4814287".PN.	USPAT; USOCR	OR	ON	2005/11/19 05:46

S39	1	"4776924".PN.	USPAT; USOCR	OR	ON	2005/11/19 05:46
S41	10	@ad<="20030416" and ('titanium carbide' or 'titanium boride' or 'titanium nitride') with 'substrate' same 'MEMS'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 05:59
S42	24	@ad<="20030416" and ('titanium carbide' or 'titanium boride' or 'titanium nitride') with 'substrate' same 'Microstructure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:17
S43	1	"20020185469".PN.	US-PGPUB	OR	ON	2005/11/19 06:02
S44	1	"20010054315".PN.	US-PGPUB	OR	ON	2005/11/19 06:06
S45	1	"6208013".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:06
S46	1	"20010054315".PN.	US-PGPUB	OR	ON	2005/11/19 06:08
S47	1	"6208013".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:08
S48	1	"6051866".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:08
S49	1	"6051866".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:08
S50	1	"6012336".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:08
S51	1	"6208013".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:10
S52	1	"5072288".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:10
S53	1	"5149673".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:10
S54	1	"6635509".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:15
S55	1	"6635509".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:19
S56	1	"6335224".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:19
S57	1	"6297072".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:19
S58	1	"6297072".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:21
S59	1	"6265246".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:21
S60	1	"6232150".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:21
S61	133	@ad<="20030416" and 'microstructure' same 'metal substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 06:44
S62	1	"20020115016".PN.	US-PGPUB	OR	ON	2005/11/19 06:34

S63	1	"20020093119".PN.	US-PGPUB	OR	ON	2005/11/19 06:35
S64	1	"6699643".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:37
S65	1	"6644537".PN.	USPAT; USOCR	OR	ON	2005/11/19 06:38
S66	2	("5,190,637").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/19 06:44
S67	17	@ad<="20030416" and 'metal wafer' and 'etch' same ('trench' or 'via') same 'anisotropic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:16
S68	0	@ad<="20030416" and 'titanium carbide' with 'substrate' same 'MEMS'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:18
S69	1337	@ad<="20030416" and 'titanium carbide' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:19
S70	0	@ad<="20030416" and 'titanium carbide' with 'substrate' same ('trench' or 'via') same 'anisotropic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:19
S71	46	@ad<="20030416" and 'titanium carbide' with 'substrate' same 'via'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:25
S72	1	@ad<="20030416" and 'titanium carbide' with 'substrate' same 'trench'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:26
S73	2	@ad<="20030416" and 'titanium boride' with 'substrate' and 'MEMS'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:25
S74	8	@ad<="20030416" and 'titanium carbide' with 'substrate' and 'MEMS'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:57
S75	36	@ad<="20030416" and 'titanium nitride' with 'substrate' and 'MEMS'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:44

S76	1	"5072288".PN.	USPAT; USOCR	OR	ON	2005/11/19 07:41
S77	1	"5285097".PN.	USPAT; USOCR	OR	ON	2005/11/19 07:41
S78	1	"5316979".PN.	USPAT; USOCR	OR	ON	2005/11/19 07:42
S79	1	"5393375".PN.	USPAT; USOCR	OR	ON	2005/11/19 07:43
S80	8	@ad<="20030416" and 'titanium nitride' with 'substrate' and 'Nanostructures'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:53
S81	1	"20030174384".PN.	US-PGPUB	OR	ON	2005/11/19 07:46
S82	1	"6582767".PN.	USPAT; USOCR	OR	ON	2005/11/19 07:46
S83	1	"6521285".PN.	USPAT; USOCR	OR	ON	2005/11/19 07:46
S84	5	@ad<="20030416" and 'titanium carbide' with 'substrate' and 'Nanostructures'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:53
S85	1	@ad<="20030416" and 'titanium boride' with 'substrate' and 'Nanostructures'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:54
S86	655	@ad<="20030416" and 'metal' same 'MEMS device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:57
S87	271	@ad<="20030416" and 'metal' with 'MEMS device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 07:57
S88	1	@ad<="20030416" and 'metal plate' with 'MEMS device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 08:02
S89	186	@ad<="20030416" and 'metal' with 'plate' and 'etch' same ('trench' or 'via') same 'anisotropic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 08:02
S90	20	@ad<="20030416" and 'MEMS' and 'metal' with 'plate' and 'etch' same ('trench' or 'via') same 'anisotropic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/19 08:02

S92	404	@ad<="20030416" and ('titanium carbide' or 'titanium boride' or 'titanium nitride') with 'silicon' with 'wafer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:20
S94	24	@ad<="20030416" and 'titanium carbide' with ('wafer' or 'substrate') same 'silicon wafer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:27
S95	330	@ad<="20030416" and 'titanium carbide' with ('wafer' or 'substrate') same 'silicon' with ('wafer' or 'substrate')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:28
S96	11	@ad<="20030416" and 'titanium nitride' adj1 ('wafer' or 'substrate') same 'silicon' adj1 ('wafer' or 'substrate')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:28
S97	53	@ad<="20030416" and 'titanium carbide' with ('wafer' or 'substrate') same 'silicon' adj2 ('wafer' or 'substrate')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 10:39
S98	8	@ad<="20030416" and 'titanium carbide' adj2 ('wafer' or 'substrate') same 'silicon' adj2 ('wafer' or 'substrate')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:48
S99	1	"4923716".PN.	USPAT; USOCR	OR	ON	2005/11/21 08:32
S10 0	1	"4525415".PN.	USPAT; USOCR	OR	ON	2005/11/21 08:34
S10 1	1	"4923716".PN.	USPAT; USOCR	OR	ON	2005/11/21 08:34
S10 2	1	"4810526".PN.	USPAT; USOCR	OR	ON	2005/11/21 08:34
S10 3	1	"4459338".PN.	USPAT; USOCR	OR	ON	2005/11/21 08:34
S10 4	59	@ad<="20030416" and 'titanium nitride' adj2 ('wafer' or 'substrate') same 'silicon' adj2 ('wafer' or 'substrate')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:36
S10 5	1	@ad<="20030416" and 'titanium boride' adj2 ('wafer' or 'substrate') same 'silicon' adj2 ('wafer' or 'substrate')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:35
S10 6	11	@ad<="20030416" and 'titanium nitride' adj1 ('wafer' or 'substrate') same 'silicon' adj1 ('wafer' or 'substrate')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:36

S10 7	271	'Bunshah Rointan' or 'Parsons James' or 'Stafsudd Oscar' and 'titanium'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:50
S10 8	270	'Bunshah Rointan' or 'Parsons James' or 'Stafsudd Oscar' and 'titanium' adj3 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:50
S10 9	270	'Bunshah Rointan' or 'Parsons James' or 'Stafsudd Oscar' and 'titanium' adj2 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:55
S11 0	270	'Bunshah Rointan' or 'Parsons James' or 'Stafsudd Oscar' and 'titanium carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:55
S11 1	9	('Bunshah Rointan' or 'Parsons James' or 'Stafsudd Oscar') and 'titanium carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 08:56